

**PCN20260129000.1**  
**Qualification of additional Assembly sites for select VSSOP devices**  
**Change Notification / Sample Request**

**Date:** January 29, 2026  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20260129000.1****Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
74LVC2G132DCURG4	NULL
74LVC2G241DCUTG4	NULL
74LVC2G132DCUTG4	74LVC2G132DCUTG4
SN74LVC2G132DCUT	SN74LVC2G132DCUT
SN74LVC1G139DCUT	SN74LVC1G139DCUT
74LVC2G125DCUTG4	NULL
SN74LVC2G126DCUT	SN74LVC2G126DCUT
SN74LVC2G241DCUR	SN74LVC2G241DCUR
SN74LVC2G125DCUT	SN74LVC2G125DCUT
SN74LVC2G126DCUR	SN74LVC2G126DCUR
TS5A3357DCUR	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	PCN#20260129000.1	<b>PCN Date:</b>	January 29, 2026
<b>Title:</b>	Qualification of additional Assembly sites for select VSSOP devices		
<b>Customer Contact:</b>	Change Management Team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	April 29, 2026	<b>Sample requests accepted until:</b>	March 30, 2026*

**\*Sample requests received after March 30, 2026 will not be supported.**

**Change Type:**

<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process

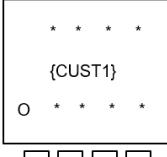
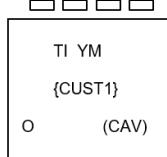
**PCN Details**

**Description of Change:**

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

VSSOP Build sites	
Assembly Sites	MLA, TIEMA, HFTF, HNA
Mount Compound	4147858
	SID#A-18
	4213245
	SID#400180
	SID#400194
Mold Compound	4211880
	4222198
	SID#R-31
	SID#450179
	8096859
Lead frame Finish	NiPdAu, Matte Sn
Bond Wire (mil)	Au, Cu (0.8mil, 1.0mil)

**Device marking:**

	<b>Current</b>	<b>Additional</b>
Marking differences	Pin 1 dimple Binary code 	Pin 1 dot Mold cavity ID 

**Reason for Change:**

Continuity of Supply

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

**RoHS**

**REACH**

**Green Status**

**IEC 62474**

<input checked="" type="checkbox"/> No Change			
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**Changes to product identification resulting from this PCN:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
MLA	MLA	MYS	Kuala Lumpur
TIEMA	CU6	MYS	Melaka
HFTF	HFT	CHN	Hefei
HNA	HNT	THA	Ayutthaya

Sample product shipping label (not actual product label)



**Product Affected:**

74LVC1G139DCURG4	74LVC2G241DCURE4	SN74LVC2G126DCUT
74LVC1G139DCUTG4	74LVC2G241DCURG4	SN74LVC2G132DCUT
74LVC2G125DCURE4	74LVC2G241DCUTG4	SN74LVC2G241DCUR
74LVC2G125DCURG4	SN74LVC1G139DCUR	SN74LVC2G241DCUT
74LVC2G125DCUTG4	SN74LVC1G139DCUT	TS5A3357DCUR
74LVC2G126DCUTG4	SN74LVC2G125DCUR-S	TS5A3357DCURG4
74LVC2G132DCURG4	SN74LVC2G125DCUT	
74LVC2G132DCUTG4	SN74LVC2G126DCUR	

Note: G4/E4 material will use NiPdAu lead finish

## VSSOP Qualification Report

**Data Displayed as: Number of lots / Total sample size / Total failed**

	Stress Test	Duration	HFTF <b>SN74LVC1G123DCU TMUX7219DGKQ1 SN74AXC2T45QDCURQ1</b>	MLA <b>SN74LVC2T45QDCURQ1 CLXC8T245QDGSRQ1 LSF0108DGSR</b>
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (PGA308AIDGSR)	3/66/0 (LMH5485DGKSEP)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HNA <b>TPS77301DGK TMP431ADGK SN74LVC2G125DCUR</b>	TIEMA <b>LM3489QMM LM5067MM-2NOPB</b>
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	-
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	1/77/0	-
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TS5A23160DGSR)	3/66/0 (LM2660MM/NOPB)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass

CLXC8T245QDGSRQ1, TPS77301DGK, TMUX7219DGKQ1, LM3489QMM, LSF0108DGSR, LM5067MM-2NOPB, SN74LVC2T45QDCURQ1, SN74LVC1G123DCU, SN74AXC2T45QDCURQ1, SN74LVC2G125DCUR are qualified at L1-260C MSL rating.

TMP431ADGK is qualified at L2-260C MSL rating.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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